

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: H. MATSUURA, et al.  
Application No.: 10/519,713  
Filed: DECEMBER 30, 2004  
For: ADHESIVE FILM FOR SEMICONDUCTOR USE, METAL  
SHEET LAMINATED WITH ADHESIVE FIL, WIRING CIRCUIT  
LAMINATED WITH ADHESIVE FILM, AND SEMICONDUCTOR  
Group AU: 2823  
Examiner: Julio J. Maldonado  
Confirm. No.: 7508

**AMENDMENT**

**Mail Stop: AMEND - FEE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

September 17, 2007

Sir:

In response to the Office Action mailed May 15, 2007, the period for response having been extended for one (1) month by the attached Petition for Extension of Time, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.